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Amendments to the Specification: Please replace Paragraph [0036] with the following replacement paragraph:

[0036] As shown in FIG. 7, after the opening is formed, the metal (preferably copper) which is used to form the redistribution conductor ~~211~~ 221 is electroplated onto the exposed portion of the metallization 209. The photoresist is then stripped, and the exposed metallization 209 is removed with an appropriate etch as shown in FIG. 8. For example, if the metallization 209 comprises a conductive release layer 211 of TiW and a conductive seed layer 213 of copper, the conductive seed layer 213 may be removed with a chlorite or persulfate copper etchant using a spray acid tool or, alternatively, in an agitated bath, and the conductive release layer 211 may be removed with a hot hydrogen peroxide solution. Preferably, the conductive release layer 211 and the conductive seed layer 213 are sufficiently thin that the exposed portions of these layers are removed after only brief exposure to these etchants. Moreover, it is preferred that the redistribution conductor 221 is sufficiently thick compared to the conductive release layer 211 and the conductive seed layer 213 that its dimensions are substantially unaltered by the etchants used to remove the exposed portions of these layers. As indicated in FIG. 10, etching of the conductive release layer 211 and the conductive seed layer 213 may result in a

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slight amount of undercutting underneath the redistribution
conductor 221 and the bump contact 231 (see FIG. 10).